High Speed Practical Polymer Optical Waveguides Demonstrated in 24 ch x 16 Gbps Optical Interconnection Module for Computercom System

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Ideal Optical Interconnection Structure On-board Level²

Polymer waveguides are fabricated on PCB/ embedded in PCB



Model of O/E board example

<u>Merits</u>

- \checkmark High bandwidth,
- ✓ Low-power dissipation
- ✓ Compact-size
- ✓ Available conventional SMT

Demerits as regards waveguide

- ✓ Reliability after reflow process✓ CTE mismatching
- ✓ Difference of allowance between electrical circuit and optical one



Proposal of Flex Optical/Electrical (0/E) Module ³



Comparison between Two Structures

		On board/ embedded waveguide in PCB	Flex O/E module		
Design	Limitation	Circuit design specifications	Thermal controls 🔅		
Fabrication	process	One by one, Continuous	Separate, Assembly		
	Control of narrow allowance	All points at optics area on/in the board	Waveguide 😳		
	Yield	Low (Exponential function 🕃 of each process)	High (Separated each 😳 process)		
	Optical connector	Hard to fabricate	Easy		
After fabrication	Mounting	conventional SMT	Some assembling process 🔅		
	Reliability	Hard requirements	Keeping each parts		
	Optics Repair	Depends on systems	Possible 😳		
Flex O/E module has a big potential to realize reasonably					

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Demonstration of Simple Flex O/E Module



- Bi-directionally linking by waveguide
- Two flexible printed circuit (FPC) boards with 12ch Tx & 12ch Rx
- FPC and waveguide were independently fabricated and they are precisely hybridized by standard packaging process.



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Optical Circuit Design (waveguide)



Unique Low Loss Polymer Waveguide



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Merits of SB's Waveguides



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Electrical Board Design (FPC portion)

Electrical board design as a platform for O/E conversion

21	_			լμՠյ	
		Cross section	Design	Measure	
	Board size : 21.00 mm x 17.20 mm	Solder resist	15±10	15± 7	
		Cu plating	6± 3	14± 5	
2 1	: 2.50 mm	Cu foil	8±2		
	VD-TIA space	Polyimide	25± 3	25± 3	
Rx	: 1.82 mm	Cu foil	8±2	14± 5	
		Cu plating	6±3		
Single end Different	ial end				
		VCSEL-VD (Sing	<u>le end)</u>		
	Line width	: 50 μm	Line len	igth : 1 mi	m
		VD-Probe (Differe	ntial end)		
		ine/Space : 40/40	ım	-	
	Line length	: CH1,12 : 1.95 m	m / CH2,	11:3.55 mn	n
		CH3.10:4.60 m	m / CH4.9	: 5.75 mm	ו
		CH5,8 : 6.95 m	m / CH6,7	': 8.10 mm	۱

Related transmission loss was verified to be very small and negligible



Data Transmission Measurement

Measurement set-up



O/E transceiver module





Data Transmission @16Gbps/ch



- Wide eye opening was observed under the condition of data transmission at 16 Gbps/ch.
- Bit error ratio of every channel was less than 10⁻¹².
- Around 400Gbps data transmission(Tx1 \rightarrow Rx2,Tx2 \rightarrow Rx1) was successfully achieved.



Key Points of Flex O/E Module

Mirrors

To reduce the footprint of MCM, Optics & waveguide pitch need high-density

Conventional method



Cross sectional view

Crossed waveguide

- One of merits; waveguide can have crossed light paths in the same circuit plane.
- ✓ Hard to form uniformly✓ Bad crossing loss

✓ Hard to stack multi layers
✓ Increasing cost
✓ Hard to keep reliability



High density 45-degree Mirror



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Low Crossing Loss



Key Points of Flex O/E Module



Reliability of SB's Waveguides with 45-degree Mirrors¹⁶

	condition	result
High Temperature Reliability Test	1000Hr at 125 deg. C	± 0.3 dB*
Low Temp. Reliability Test	1000Hr at - 40 deg. C	± 0.3 dB*
High Temp. and Humidity Reliability Test	$85\pm$ 2 deg. C, $85\pm$ 5% (RH), 1000 Hr	±0.3dB*
High Temp. and Humidity Reliability Test	A. 75 deg. C, 85~95% RH, for 8hours B. R.T., 80~100% RH C40 deg. C, for 8hours 5 cycles	±0.3dB*
Thermal Shock Test	Temp.Time1) - $40 \pm 3 \deg$. C30min2) $85 \pm 3 \deg$. C30min100 cycles30min	±0.3dB*

* ± 0.3 dB = the margin of error in loss measurement



Comparison about Cost- effectiveness decrease increase same

		On board/ embedded waveguide PCB	Flex O/E module
Design	limitation	Circuit design specifications	Thermal controls
Fabrication	process	One by one, Continuous	Separate, Assembly 🔤 😥
	Control of narrow allowance	All points at optics area on/in the board	Care only Waveguide
	Yield	Low (Exponential function 🕃 of each process)	High (Separated each C) process)
	Optical connector	Hard to fabricate 🙁	Simple fabrication CC CC Process
After fabrication	Mounting	Easy (only SMT)	Some assembling proces 😒
	Reliability	Hard requirements	Keeping each parts
	Optics Repair	Depends on systems	Possible
		Total costs decrease	◆ は友べークライト株式会社







Type A) Optical WG Sheet /with 45° mirror





Type B) Optical WG Sheet with PMT connector

~12ch/250um pitch/1layer ~24ch/125um pitch/1layer Type C) Optical WG Sheet with MPO connector (under development)

